

DESCRIPTION and APPLICATIONS

Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

VOLTAGE RANGE

50 to 1000 Volts

CURRENT

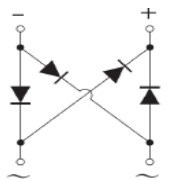
0.8 Ampere

FEATURES

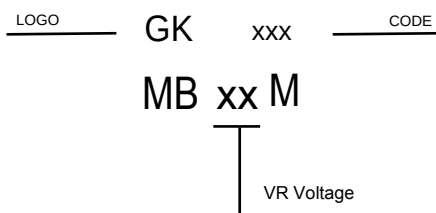
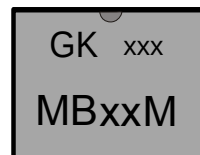
- * Ideal for printed circuit board
- * Reliable low cost construction utilizing molded plastic technique
- * High surge current capability

MECHANICAL DATA

- * Polarity: Symbol molded on body
- * Mounting position: Any
- * Weight: 0.14grams



Internal Schematic



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	MB05M	MB1M	MB2M	MB4M	MB6M	MB8M	MB10M	UNIT
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	0.8							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	3.0							A
Maximum Forward Voltage Drop per Bridge Element at 0.4A D.C.	1.0							V
Maximum DC Reverse Current Ta=25°C	5.0							μA
at Rated DC Blocking Voltage Ta=125°C	500							μA
Typical Thermal Resistance R _{JA} (Note 2)	75							°C/W
Operating Temperature Range, T _J	-55 — +150							°C
Storage Temperature Range, T _{STG}	-55 — +150							°C

NOTES: 1. Mounted on P.C. Board.
2. Thermal Resistance Junction to Ambient.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

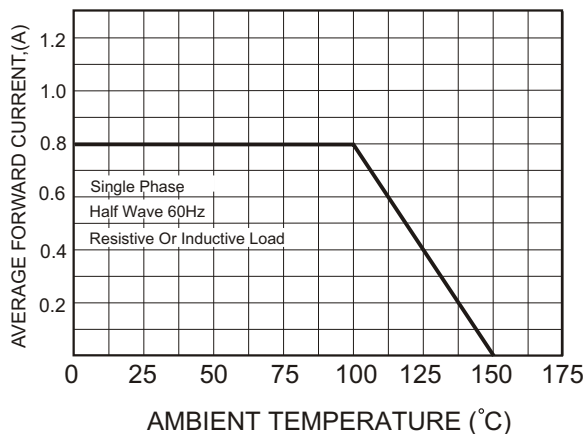


FIG.2-TYPICAL FORWARD CHARACTERISTICS

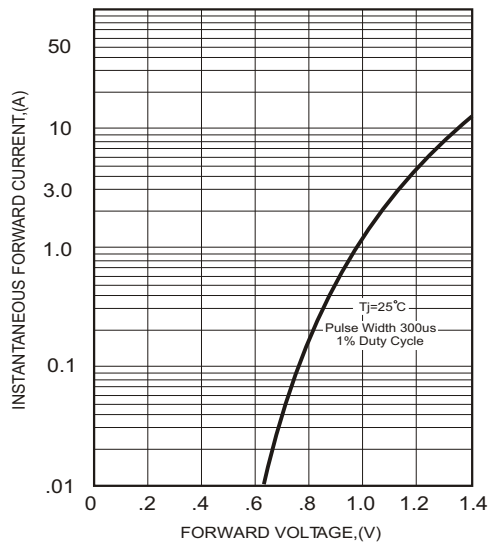


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

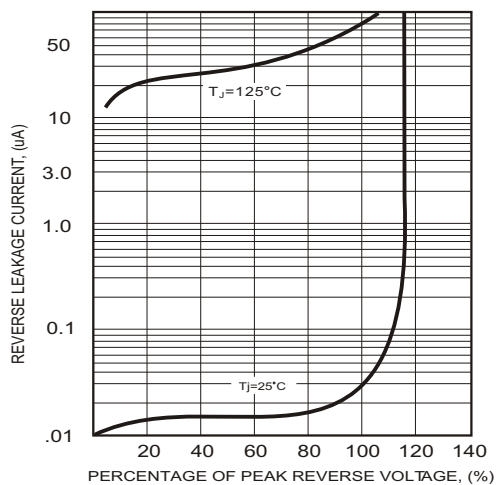
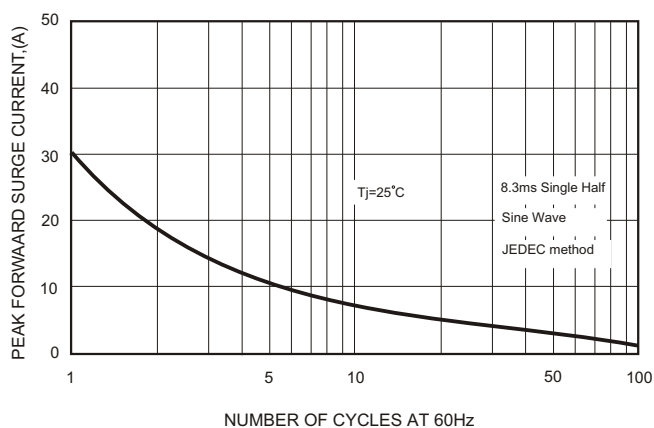
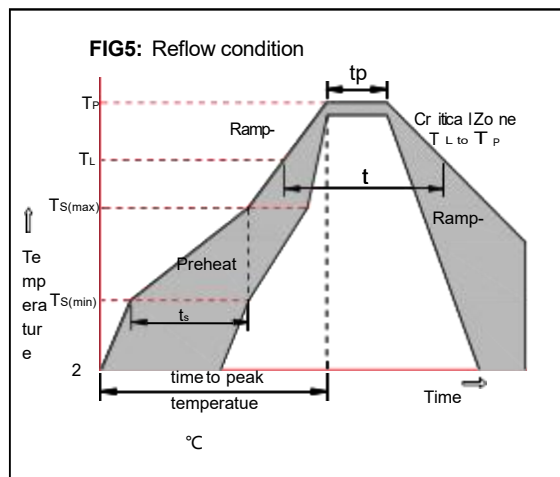


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

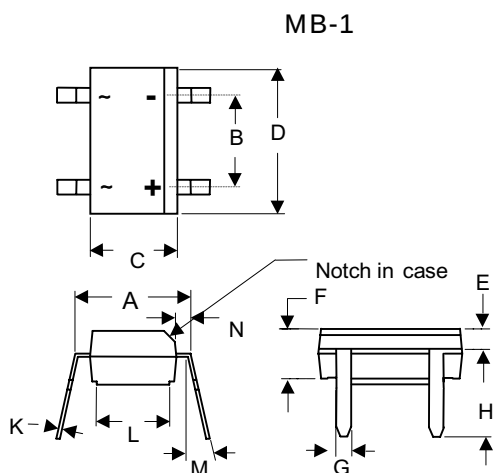


Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout



Case Style					
DIMENSIONS					
DIM	INC HES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.195	.205	4.95	5.21	
B	.095	.105	2.41	2.67	
C	.144	.161	3.65	4.10	
D	.179	.190	4.55	4.83	
E	.039	.049	0.99	1.24	
F	.090	.106	2.30	2.70	
G	.017	.029	0.43	0.74	
H	.132	.148	3.35	3.75	
K	.006	.016	0.15	0.41	
L	.137	.147	3.48	3.73	
M	10°	15°	10°	15°	
N	.020	.028	0.51	0.71	